

**PAT-NO:** JP403126538A  
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**TITLE:** RESIN SHEET WITH RELEASE SHEET AND MULTILAYERED INTERCONNECTION BOARD  
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**INVENTOR-INFORMATION:**

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**ABSTRACT:**

**PURPOSE:** To obtain a multilayered interconnection board

having excellent high- frequency characteristics by coating a release sheet with resin varnish, in which a thermoplastic resin, triaryl isocyanurate, a flame retarder, a reaction initiator and a solvent are added to polyphenylene oxide and fillers are added as required, and drying the varnish.

CONSTITUTION: Even modified polyphenylene oxide is used, and 20-70 pts.wt. loads are favorable. A resin compatible with a polyphenylene oxide resin may be employed as a thermoplastic resin, and 2-30 pts.wt. loads are preferable. A monomer or a prepolymer can be used as triaryl isocyanurate, and 10-70 pts.wt. loads are favorable. A tetrabromobisphenol A derivative, a bromization aromatic compound, etc., are preferable as a flame retarder, and loads are not limited particularly. An organic peroxide is used as a reaction initiator, and 1-5 pts.wt. loads are favorable.

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